X13 5G Edge

Short-depth Rackmount Systems for Telco and Network Edge Deployments

High-density processing power and data throughput with front access I/O design

- Single 4th Gen Intel® Xeon® Scalable processor
- Dual 10Gb Ethernet connection
- Flexible configuration with up to 3 PCIe 5.0 slots in 1U or 4 slots in 2U
- Front I/O, power and serviceability for space constrained edge environments
- Both AC and DC power configurations available with redundant power supplies
- Enhanced operating temperatures from -5°C to 55°C (CPU TDP-dependent)

Processing Power at the Network Edge

X13 5G Edge systems offer powerful, high-throughput computing platforms with expanded I/O, delivering device-to-device communications with compact and power efficient configurations. Supermicro's family of networking and embedded products are optimized for a wide range of applications, including RAN, MEC and security. Supermicro offers many flexible and customized solutions for critical OEM projects, as well as advanced designs for stringent environments, firmware customization, BOM enhancements, and a wide range of legacy I/O support.

High Flexibility and Data Throughput

Supermicro's 5G Edge systems offer a high level of customization, with up to 4 PCIe 5.0 slots for add-on cards. This allows each system to be fully further optimized to specific workloads, such as AI inferencing, Multi-Access Edge Computing, or RAN. Deployed in this fashion, the systems are also ideal to leverage Intel's vRAN Boost technology, further increasing the platform's efficiency and reducing power consumption by up to 20% on vRAN workloads.

Remote Data Center Deployment

Designed for remote and space-constrained telco environments, these short-depth systems are available with both AC and DC redudant power options. Their front I/O design makes management easier and an enhanced operating temperature from -5°C to 55°C means these systems are capable of running well beyond the regular data center parameters.

SUPERMICRO

5G Edge	SYS-211E-FRN2T/FRDN2T	SYS-111E-FWTR/FDWTR
Processor Support	Single Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processor[†]	Single Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processor[†]
Memory Slots & Capacity	8 DIMM slots; Up to 2TB 3DS ECC DDR5-4800: RDIMM/LRDIMM	8 DIMM slots; Up to 2TB 3DS ECC DDR5-4800: RDIMM/LRDIMM
Outstanding Features	Design with compliance to NEBS Level 3	Redundant power supplies Front access IO design, 16.9" (430mm) chassis depth 5G Telecom, Flex-RAN, Open-RAN Optimized
I/O Ports	1 RJ45 Dedicated BMC LAN port 2 USB 2.0 port(s) 2 USB 3.0 port(s) 1 VGA port(s) 1 COM Port(s)	1 RJ45 Dedicated IPMI LAN port 2 RJ45 10GbE (Intel® X550-AT2) 2 USB 2.0 port(s) 2 USB 3.0 port(s) 1 VGA port 1 COM Port
Motherboard	X13SEM-TF	X13SEW-TF
Form Factor	2U Rackmount Enclosure: 436.88mm x 88.9mm x 298.8mm(17.2"x 3.5"x 11.8") Package: 7.4" (H) x 19.3" (W) x 23.3" (D)	1U Rackmount Enclosure: 436.88 x 44.5 x 429.3mm (17.2" x 1.7" x 16.9") Package: 685 x 203 x 609mm (27" x 8" x 24")
Expansion Slots	PCIe 5.0 x16 HHHL slot(s) PCIe 5.0 x8 HHHL slot(s) 2 PCIe 5.0 x16 FHHL slot(s)	2 PCIe 5.0 x16 FHFL, PCIe 5.0 x16 LP
Drive Bays	2x 2.5" hot-swap drive bays; 2x 2.5" NVMe dedicated	2x 2.5" SATA drive bays
Cooling	4 heavy duty fan(s)	4 heavy duty fan(s)
Power	800W Redundant AC redundant power supply (SYS-211-FRN2T) 600W Redundant short depth DC48V input power supply (SYS-211E-FRDN2T)	800W AC Redundant PSU (SYS-111E-FWTR) 600W DC Redundant PSU (SYS-111E-FDWTR)

[†] Supports up to 270W TDP CPUs (Aircooled). CPUs with high TDP supported under specific conditions. Contact Technical Support for details.

SUPERMICRO